

APPROVAL SHEET

MODEL NO.: SMD1210-050-30V

CUSTOMER:

CUSTOMER'S APPROVAL:

AUTHORIZED SIGNATURE/STAMP:

DATE

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Submitted by: Approved by: DATE: Chung Cheng YC Lin 11-Apr-13

SEA & LAND ELECTRONIC CORP.



SMD1210-050-30V

Features

Surface Mount Devices

- Lead free device
- Size 3.2*2.5mm/0.12*0.10 inch protected, including:
- Surface Mount packaging Computer mother board, Modem. for automated assembly

Telecommunication equipments.

Almost anywhere there is a low voltage

power supply, up to 30V and a load to be

Applications

Alpha-Top (Sea&Land Alliance)

Model	Marking	V _{max}	I _{max}	hold	I _{trip}	Pd	Maximum Time To Trip		Resistance		Agency Approval	
Model	Marking			@25°C	@25°C	Тур.	Current	Time	Ri _{min}	R1 _{max}	UL	τυν
		(Vdc)	(A)	(A)	(A)	(W)	(A)	(Sec)	(Ω)	(Ω)		
SMD1210-050-30V	αF	30.0	100	0.50	1.00	0.60	8.0	0.10	0.180	0.900		
Ihold = Hold Current. I	Maximum cui	rrent device v	vill not trip i	in 25°C still a	ir.							
Itrip = Trip Current. M	inimum curre	ent at which t	he device v	vill always trip	o in 25°C still	air.						
Vmax = Maximum oper	ating voltage	e device can	withstand w	vithout dama	ge at rated cu	urrent (Ima:	x).					
Imax = Maximum faul	t current devi	ice can withs	tand withou	ut damage at	rated voltage	e (Vmax).						
Pd = Power dissipati	on when dev	rice is in the t	ripped state	e in 25°C still	air environm	ent at rated	d voltage.					
Rimin/max = Minimum	/Maximum de	evice resistar	nce prior to	tripping at 28	5°C.							
R1 _{max} = Maximum dev	ice resistanc	e is measure	d one hour	post reflow.								
CAUTION : Operation b	eyond the sp	pecified rating	gs may resu	ult in damage	and possible	e arcing an	d flame.					

Environmental Specifications

Test	Conditions	Resistance change			
Passive aging	+85°C, 1000 hrs.	±5% typical			
Humidity aging	+85°C, 85% R.H. , 168 hours	±5% typical			
Thermal shock	+85°C to -40°C, 20 times	±33% typical			
Resistance to solvent	MIL-STD-202, Method 215	No change			
Vibration	MIL-STD-202, Method 201	No change			
Ambient operating conditions : - 40 °C to +85 °C					
Maximum surface temperature of the device in the tripped state is 125 °C					

AGENCY APPROVALS :		UL pending
Regulation/Standard:	PoRHS	2002/95/EC
	HF	EN14582

Ihold Versus Temperature

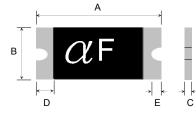
Mod	al	Maximum ambient operating temperature (T_{mao}) vs. hold current (I_{hold})									
Model	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C		
SMD1210-	050-30V	0.76	0.67	0.58	0.50	0.43	0.40	0.36	0.32	0.28	

SMD1210-050-30V

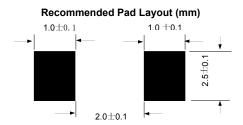
Alpha-Top (Sea&Land Alliance)

Construction And Dimension (Unit:mm)									
Medal	Α		В		С		D	E	
Model	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Min.	
SMD1210-050-30V	3.00	3.43	2.35	2.80	0.30	0.80	0.30	0.10	

Dimensions & Marking







Termination Pad Characteristics

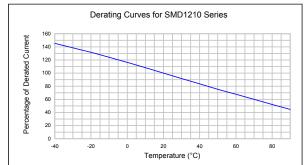
Terminal pad materials : Terminal pad solderability :

Tin-plated Nickel-Copper Meets EIA specification RS186-9E and ANSI/J-STD-002 Category 3.

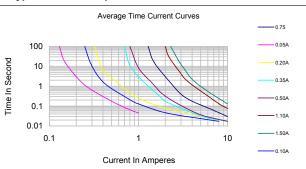
Rework

Use standard industry practices, the removal device must be replaced with a fresh one.

Thermal Derating Curve



Typical Time-To-Trip At 25°C



WARNING:

· Use PPTC beyond the maximum ratings or improper use may result in device damage and possible electrical arcing and flame. • PPTC are intended for protection against occasional over current or over temperature fault conditions and should not be used when repeated fault conditions or prolonged trip events are anticipated.

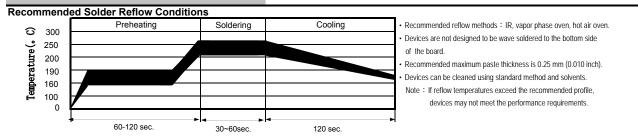
• Device performance can be impacted negatively if devices are handled in a manner inconsistent with recommended electronic, thermal, and mechanical procedures for electronic components. • Use PPTC with a large inductance in circuit will generate a circuit voltage (L di/dt) above the rated voltage of the PPTC.

Avoid impact PPTC device its thermal expansion like placed under pressure or installed in limited space

· Contamination of the PPTC material with certain silicon based oils or some aggressive solvents can adversely impact the performance of the devices. PPTC SMD can be cleaned by standard methods.

· Requests that customers comply with our recommended solder pad layouts and recommended reflow profile. Improper board layouts or reflow profile could negatively impact solderability performance of our devices.

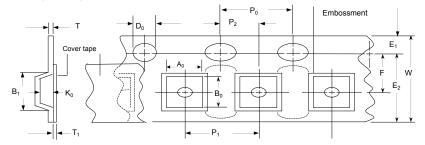
SMD1210-050-30V



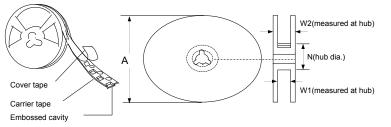
Tape And Reel Specifications (mm)

EIA Tape Component Dimensions

Governing Specifications	EIA 481-2
W	8.0 ± 0.20
P0	4.0 ± 0.10
P1	4.0 ± 0.10
P2	2.0 ± 0.10
A0	2.82 ± 0.10
В0	3.52± 0.10
B1max.	4.35
D0	1.5 + 0.1, -0.0
F	7.5 ± 0.05
E1	1.75 ± 0.10
E2min.	6.25
Tmax.	0.6
T1max.	0.1
КО	0.90 ± 0.1
Leader min.	390
Trailer min.	160
Reel Dimensions	
A max.	178
N min.	50
W1	8.4 + 1.5, -0.0
W2max.	22.4



EIA Reel Dimensions



Storage And Handling

- Storage conditions : 40°C max, 70% R.H.
- · Devices may not meet specified performance
- if storage conditions are exceeded.

Order Information

Order Information	Packaging					
SMD1210	050	-30V	Tape & Reel Quantity			
Product name	Hold	Max				
Size 3225 mm / 1210 inch	Current	Voltage	4,000 pcs/reel			
SMD : surface mount device	0.50A					

Tape & reel packaging per EIA481-1

Labeling Information

